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ESD Association Technical Report

***For the Protection of Electrostatic
Discharge Susceptible Items***

***Transmission Line Pulse
Round Robin***

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FOREWORD

This document was prepared by the ESD Association Working Group 5.5, Transmission Line Pulse. It is intended to provide data on the repeatability and reproducibility limits of the methods of SP5.5.1 TLP Standard Practice.

Recommendations from the ASTM E691 were incorporated in this round robin study. Those being: 5 test labs participated in data collection, test samples used were homogenous and identical, first set of identical structures tested to failure, a second set of structures were passed from lab to lab, all data was collected and analyzed to determine the reproducibility of the TLP test method.

This technical report round robin is intended to support the repeatability of the TLP standard practice method in order that it may be elevated to a standard test method.

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